IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mi	als and Mfg Information					
Supplie	r Information															
Company name* Company uniqu				que ID			Unique ID Authority					Response Date*				
onsemi													2024-05-19			
Contact N	Vame	Title - Contact]	Phone - Contact*					Email - Contact*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*						
Product-1	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	te Versi	ion 1	Manufacturing Site		V	Veight*	UOM	Unit Type	
		FOD3182 8PW		8PW 3A GD DIP			2024-05-19		1	LITEONFG		5	98.06665	mg	Each	
Manufa	acturing Proccess Informati	on		1				,						1	-	
	Terminal Plating / Grid Array Material Te		erminal Base Alloy J-STD-02		J-STD-020 MSL	Rating	Peak Process Body Temperat		ly Temperatu	ure Max Time at Peak Temper		Temperati	are Numb	per of Reflow Cyc	les	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0	0 C		30 seco		secono	is 3				
Comments	S															
or more	information regarding material c	omposition]	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction this form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	209.511	mg	Supplier	Filler (SiO2)	68909-20-6		94.2799	mg
			Supplier	Xylene	1330-20-7		115.2311	mg
Die	1.11668	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.0068	mg
			Supplier	Silicon (Si)	7440-21-3		1.1099	mg
Die Attach	0.25	mg	Supplier	Silver (Ag)	7440-22-4		0.2	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0275	mg
			Supplier	Dicyandiamine	461-58-5		0.005	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.0175	mg
Lead Frame	115.0	mg	Supplier	Silver (Ag)	7440-22-4		0.7476	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1438	mg
			Supplier	Iron (Fe)	7439-89-6		2.7028	mg
			Supplier	Copper (Cu)	7440-50-8		111.311	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0949	mg
Mold Compound-Black	260.539	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		52.1018	mg
			Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		6.5427	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		32.5637	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.1178	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		130.2544	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		29.9585	mg
Plating	11.6	mg	Supplier	Tin (Sn)	7440-31-5		11.6	mg
Wire Bond - Au	0.05	mg	Supplier	Gold (Au)	7440-57-5		0.05	mg